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Details

Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	20MHz
Connectivity	I ² C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	4
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.154", 3.90mm Width)
Supplier Device Package	8-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08qg4cdne

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Chapter 4 Memory Map and Register Definition

Address	Register Name	Bit 7 6 5 4 3		3	2	1	Bit 0		
0x00 14	ADCCVH	0	0 0		0	0	0	ADCV9	ADCV8
0x00 15	ADCCVL	ADCV7	ADCV6	ADCV5	ADCV4	ADCV3	ADCV2	ADCV1	ADCV0
0x00 16	ADCCFG	ADLPC	AD	NV	ADLSMP	MODE		ADI	CLK
0x00 17	APCTL1	ADPC7	ADPC6	ADPC5	ADPC4	ADPC3	ADPC2	ADPC1	ADPC0
0x00 18	Reserved	0	0	0	0	0	0	0	0
0x00 19	Reserved	0	0	0	0	0	0	0	0
0x00 1A	ACMPSC	ACME	ACBGS	ACF	ACIE	ACO	ACOPE	ACM	NOD
0x001 B – 0x001 F	Reserved	_	_		_			_	_
0x00 20	SCIBDH	0	0	0	SBR12	SBR11	SBR10	SBR9	SBR8
0x00 21	SCIBDL	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
0x00 22	SCIC1	LOOPS	SCISWAI	RSRC	М	WAKE	ILT	PE	PT
0x00 23	SCIC2	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
0x00 24	SCIS1	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
0x00 25	SCIS2	0	0	0	0	0	BRK13	0	RAF
0x00 26	SCIC3	R8	T8	TXDIR	TXINV	ORIE	NEIE	FEIE	PEIE
0x00 27	SCID	Bit 7	6	5	4	3	2	1	Bit 0
0x00 28	SPIC1	SPIE	SPE	SPTIE	MSTR	CPOL	CPHA	SSOE	LSBFE
0x00 29	SPIC2	0	0	0	MODFEN	BIDIROE	0	SPISWAI	SPC0
0x00 2A	SPIBR	0	SPPR2	SPPR1	SPPR0	0	SPR2	SPR1	SPR0
0x00 2B	SPIS	SPRF	0	SPTEF	MODF	0	0	0	0
0x00 2C	Reserved	0	0	0	0	0	0	0	0
0x00 2D	SPID	Bit 7	6	5	4	3	2	1	Bit 0
0x00 2E	Reserved	—	—		—	_		—	—
0x00 2F	Reserved	—	—		—	_		—	—
0x00 30	IICA					0			
0x00 31	liCF	ML	JLT						
0x00 32	licc	IICEN	IICIE	MST	TX	TXAK	RSTA	0	0
0x00 33	lics	TCF	IAAS	BUSY	ARBL	0	SRW	liCIF	RXAK
0x00 34	licd				DA	TA			
0x00 35	Reserved	—	—	—	—	—	—	—	—
0x00 36	Reserved	—	—	—	—	-	-	—	—
0x00 37	Reserved	—	—	—	—	-	-	—	—
0x00 38	ICSC1	CL	KS		RDIV		IREFS	IRCLKEN	IREFSTEN
0x00 39	ICSC2	BE	VIV	RANGE	HGO	LP	EREFS	ERCLKEN	EREFSTEN
0x00 3A	ICSTRM				TF	IM			
0x00 3B	ICSSC	0	0	0	0	CLKST		OSCINIT	FTRIM
0x00 3C	MTIMSC	TOF	TOIE	TRST	TSTP	0	0	0	0
0x00 3D	MTIMCLK	0	0	CL	KS		Р	S	
0x00 3E	MTIMCNT				CO	JNT			
					-				



5.8.1 Interrupt Pin Request Status and Control Register (IRQSC)

This direct page register includes status and control bits, which are used to configure the IRQ function, report status, and acknowledge IRQ events.



Figure 5-2. Interrupt Request Status and Control Register (IRQSC)

¹ Bit 5 is a reserved bit that must always be written to 0.

Field	Description
6 IRQPDD	Interrupt Request (IRQ) Pull Device Disable — This read/write control bit is used to disable the internal pullup device when the IRQ pin is enabled (IRQPE = 1) allowing for an external device to be used. 0 IRQ pull device enabled if IRQPE = 1. 1 IRQ pull device disabled if IRQPE = 1.
4 IRQPE	 IRQ Pin Enable — This read/write control bit enables the IRQ pin function. When this bit is set the IRQ pin can be used as an interrupt request. IRQ pin function is disabled. IRQ pin function is enabled.
3 IRQF	 IRQ Flag — This read-only status bit indicates when an interrupt request event has occurred. 0 No IRQ request. 1 IRQ event detected.
2 IRQACK	IRQ Acknowledge — This write-only bit is used to acknowledge interrupt request events (write 1 to clear IRQF). Writing 0 has no meaning or effect. Reads always return 0. If edge-and-level detection is selected (IRQMOD = 1), IRQF cannot be cleared while the \overline{IRQ} pin remains at its asserted level.
1 IRQIE	 IRQ Interrupt Enable — This read/write control bit determines whether IRQ events generate an interrupt request. 0 Interrupt request when IRQF set is disabled (use polling). 1 Interrupt requested whenever IRQF = 1.
0 IRQMOD	 IRQ Detection Mode — This read/write control bit selects either edge-only detection or edge-and-level detection. See Section 5.5.2.2, "Edge and Level Sensitivity," for more details. IRQ event on falling edges only. IRQ event on falling edges and low levels.

Table 5-3. IRQSC Register Field Descriptions



1

Chapter 5 Resets, Interrupts, and General System Control

5.8.10 System Power Management Status and Control 3 Register (SPMSC3)

This high page register is used to report the status of the low voltage warning function and to select the low voltage detect trip voltage.

	7	6	5	4	3	2	1	0
R	LVWF	0			0	0	0	0
W		LVWACK	LVDV	LVWV				
POR:	0 ¹	0	0	0	0	0	0	0
LVD:	0 ¹	0	U	U	0	0	0	0
Any other reset:	0 ¹	0	U	U	0	0	0	0
		= Unimplemen	ited or Reserve	ed		U= Unaffec	ted by reset	

Figure 5-12. System Power Management Status and Control 3 Register (SPMSC3)

LVWF will be set in the case when V_{Supply} transitions below the trip point or after reset and V_{Supply} is already below V_{LVW}.

Field	Description
7 LVWF	 Low-Voltage Warning Flag — The LVWF bit indicates the low voltage warning status. 0 Low voltage warning not present. 1 Low voltage warning is present or was present.
6 LVWACK	Low-Voltage Warning Acknowledge — The LVWF bit indicates the low voltage warning status. Writing a 1 to LVWACK clears LVWF to a 0 if a low voltage warning is not present.
5 LVDV	 Low-Voltage Detect Voltage Select — The LVDV bit selects the LVD trip point voltage (V_{LVD}). 0 Low trip point selected (V_{LVD} = V_{LVDL}). 1 High trip point selected (V_{LVD} = V_{LVDH}).
4 LVWV	Low-Voltage Warning Voltage Select — The LVWV bit selects the LVW trip point voltage (V _{LVW}). 0 Low trip point selected (V _{LVW} = V _{LVWL}). 1 High trip point selected (V _{LVW} = V _{LVWH}).

Table 6-1. PTAD Register Field Descriptions

Field	Description
PTAD[5:0]	Port A Data Register Bits — For port A pins that are inputs, reads return the logic level on the pin. For port A pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port A pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTAD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pullups disabled.

6.4.1.2 Port A Data Direction (PTADD)

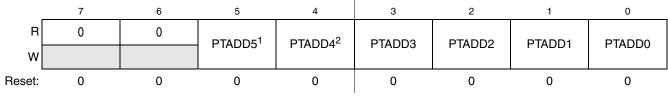


Figure 6-3. Port A Data Direction Register (PTADD)

¹ PTADD5 has no effect on the input-only PTA5 pin.

² PTADD4 has no effect on the output-only PTA4 pin.

Table 6-2. PTADD Register Field Descriptions

Field	Description
	Data Direction for Port A Bits — These read/write bits control the direction of port A pins and what is read for PTAD reads.
	 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port A bit n and PTAD reads return the contents of PTADn.

6.4.2 Port A Control Registers

The pins associated with port A are controlled by the registers in this section. These registers control the pin pullup, slew rate, and drive strength of the port A pins independent of the parallel I/O register.



7.4.5 BGND Instruction

The BGND instruction is new to the HCS08 compared to the M68HC08. BGND would not be used in normal user programs because it forces the CPU to stop processing user instructions and enter the active background mode. The only way to resume execution of the user program is through reset or by a host debug system issuing a GO, TRACE1, or TAGGO serial command through the background debug interface.

Software-based breakpoints can be set by replacing an opcode at the desired breakpoint address with the BGND opcode. When the program reaches this breakpoint address, the CPU is forced to active background mode rather than continuing the user program.



Bit-Manipulation Branch Read-Modify-Write								012)		Pagiata	Momony				
	0 5 10 5 20 3 30 5 40 1 50 1 60 5 70 4							1trol 90 3	40 0	B0 3		Memory	E0 3	F0 3	
BRSET0 3 DIR	BSET0 2 DIR	BRA 2 REL	NEG 2 DIR	NEGA 1 INH	NEGX	NEG 2 IX1	NEG 1 IX	RTI 1 INH	BGE 2 REL	A0 2 SUB 2 IMM	SUB 2 DIR	SUB 3 EXT	D0 4 SUB 3 IX2	SUB 2 IX1	SUB 1 IX
01 5	11 5	21 3	31 5	41 4	51 4	61 5	71 5	81 6	91 3	A1 2	B1 3	C1 4	D1 4	E1 3	F1 3
BRCLR0	BCLR0	BRN	CBEQ	CBEQA	CBEQX	CBEQ	CBEQ	RTS	BLT	CMP	CMP	CMP	CMP	CMP	CMP
3 DIR	2 DIR	2 REL	3 DIR	3 IMM	3 IMM	3 IX1+	2 IX+	1 INH	2 REL	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
02 5 BRSET1 3 DIR	12 5 BSET1 2 DIR	22 3 BHI 2 REL	32 5 LDHX 3 EXT	42 5 MUL 1 INH	52 6 DIV 1 INH		72 1 DAA 1 INH	82 5+ BGND 1 INH		A2 2 SBC 2 IMM		C2 4 SBC 3 EXT	D2 4 SBC	E2 3 SBC 2 IX1	F2 3 SBC 1 IX
03 5 BRCLR1 3 DIR	13 5 BCLR1 2 DIR	23 3 BLS 2 REL	33 5 COM 2 DIR	43 1 COMA 1 INH	53 1 COMX 1 INH	63 5 COM 2 IX1	73 4 COM 1 IX	83 11 SWI 1 INH		A3 2 CPX 2 IMM		C3 4 CPX 3 EXT		E3 3 CPX 2 IX1	F3 3 CPX 1 IX
04 5 BRSET2 3 DIR	14 5	24 3 BCC 2 REL	34 5 LSR 2 DIR	44 1 LSRA 1 INH			74 4 LSR 1 IX	84 1 TAP 1 INH		A4 2 AND		C4 4 AND 3 EXT		E4 3 AND 2 IX1	F4 3 AND 1 IX
05 5	15 5	25 3	35 4	45 3	55 4	65 3	75 5	85 1	95 2	A5 2	B5 3	C5 4	D5 4	E5 3	F5 3
BRCLR2	BCLR2	BCS	STHX	LDHX	LDHX	CPHX	CPHX	TPA	TSX	BIT	BIT	BIT	BIT	BIT	BIT
3 DIR	2 DIR	2 REL	2 DIR	3 IMM	2 DIR	3 IMM	2 DIR	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
06 5	16 5	26 3	36 5	46 1	56 1	66 5	76 4	86 3	96 5	A6 2	B6 3	C6 4	D6 4	E6 3	F6 3
BRSET3	BSET3	BNE	ROR	RORA	RORX	ROR	ROR	PULA	STHX	LDA	LDA	LDA	LDA	LDA	LDA
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	3 EXT	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
07 5	17 5	27 3	37 5	47 1	57 1	67 5	77 4	87 2	97 1	A7 2	B7 3	C7 4	D7 4	E7 3	F7 2
BRCLR3	BCLR3	BEQ	ASR	ASRA	ASRX	ASR	ASR	PSHA	TAX	AIS	STA	STA	STA	STA	STA
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
08 5	18 5	28 3	38 5	48 1	58 1	68 5	78 4	88 3	98 1	A8 2	B8 3	C8 4	D8 4	E8 3	F8 3
BRSET4	BSET4	BHCC	LSL	LSLA	LSLX	LSL	LSL	PULX	CLC	EOR	EOR	EOR	EOR	EOR	EOR
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
09 5	19 5	29 3	39 5	49 1	59 1	69 5	79 4	89 2	99 1	A9 2		C9 4	D9 4	E9 3	F9 3
BRCLR4	BCLR4	BHCS	ROL	ROLA	ROLX	ROL	ROL	PSHX	SEC	ADC		ADC	ADC	ADC	ADC
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	1 INH	2 IMM		3 EXT	3 IX2	2 IX1	1 IX
0A 5	1A 5	2A 3	3A 5	4A 1	5A 1	6A 5	7A 4	8A 3	9A 1	AA 2	BA 3	CA 4	DA 4	EA 3	FA 3
BRSET5	BSET5	BPL	DEC	DECA	DECX	DEC	DEC	PULH	CLI	ORA	ORA	ORA	ORA	ORA	ORA
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
0B 5	1B 5	2B 3	3B 7	4B 4	5B 4	DBNZ	7B 6	8B 2	9B 1	AB 2	BB 3	CB 4	DB 4	EB 3	FB 3
BRCLR5	BCLR5	BMI	DBNZ	DBNZA	DBNZX		DBNZ	PSHH	SEI	ADD	ADD	ADD	ADD	ADD	ADD
3 DIR	2 DIR	2 REL	3 DIR	2 INH	2 INH		2 IX	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
0C 5	1C 5	2C 3	3C 5	4C 1	5C 1	6C 5	7C 4	8C 1	9C 1		BC 3	CC 4	DC 4	EC 3	FC 3
BRSET6	BSET6	BMC	INC	INCA	INCX	INC	INC	CLRH	RSP		JMP	JMP	JMP	JMP	JMP
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	1 INH		2 DIR	3 EXT	3 IX2	2 IX1	1 IX
0D 5 BRCLR6 3 DIR	1D 5 BCLR6 2 DIR	2D 3 BMS 2 REL	3D 4 TST 2 DIR	4D 1 TSTA 1 INH	5D 1 TSTX 1 INH	6D 4 TST 2 IX1	7D 3 TST 1 IX		NOP	AD 5 BSR 2 REL	JSR 2 DIR	CD 6 JSR 3 EXT	DD 6 JSR 3 IX2	ED 5 JSR 2 IX1	FD 5 JSR 1 IX
0E 5 BRSET7 3 DIR	1E 5 BSET7 2 DIR	2E 3 BIL 2 REL	3E 6 CPHX 3 EXT	4E 5 MOV 3 DD	5E 5 MOV 2 DIX+	6E 4 MOV 3 IMD	7E 5 MOV 2 IX+D	8E 2+ STOP 1 INH	9E Page 2	AE 2 LDX 2 IMM	BE 3 LDX 2 DIR	CE 4 LDX 3 EXT	DE 4 LDX 3 IX2	EE 3 LDX 2 IX1	FE 3 LDX 1 IX
0F 5	1F 5	2F 3	3F 5	4F 1	5F 1	6F 5	7F 4	8F 2+	9F 1	AF 2	BF 3	CF 4	DF 4	EF 3	FF 2
BRCLR7	BCLR7	BIH	CLR	CLRA	CLRX	CLR	CLR	WAIT	TXA	AIX	STX	STX	STX	STX	STX
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX

Table 7-3, Opcode Map (Sheet 1 of 2)

INH	Inherent
IMM	Immediate
DIR	Direct
EXT	Extended
DD	DIR to DIR
IX+D	IX+ to DIR

REL IX IX1 IX2 IMD DIX+

Relative Indexed, No Offset Indexed, 8-Bit Offset Indexed, 16-Bit Offset IMM to DIR DIR to IX+

Stack Pointer, 8-Bit Offset Stack Pointer, 16-Bit Offset Indexed, No Offset with Post Increment Indexed, 1-Byte Offset with Post Increment

SP1 SP2 IX+

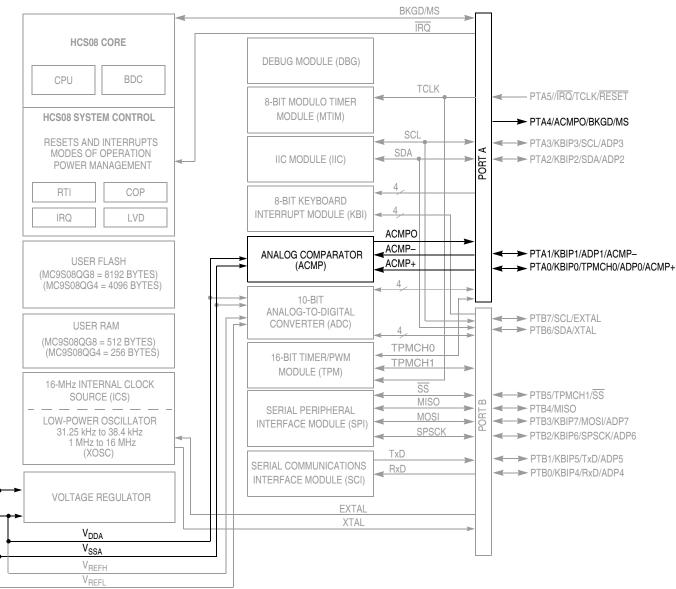
IX1+

MC9S08QG8 and MC9S08QG4 Data Sheet, Rev. 5

Opcode in Hexadecimal F0 3 SUB Instruction Mnemonic 1 IX Addressing Mode Number of Bytes



Chapter 8 Analog Comparator (S08ACMPV2)



NOTES:

V_{SS}

 V_{DD}

¹ Not all pins or pin functions are available on all devices, see Table 1-1 for available functions on each device.

- ² Port pins are software configurable with pullup device if input port.
- ³ Port pins are software configurable for output drive strength.
- ⁴ Port pins are software configurable for output slew rate control.
- ⁵ IRQ contains a software configurable (IRQPDD) pullup device if PTA5 enabled as IRQ pin function (IRQPE = 1).
- ⁶ RESET contains integrated pullup device if PTA5 enabled as reset pin function (RSTPE = 1).
- ⁷ PTA4 contains integrated pullup device if BKGD enabled (BKGDPE = 1).
- ⁸ SDA and SCL pin locations can be repositioned under software control (IICPS), defaults on PTA2 and PTA3.
- ⁹ When pin functions as KBI (KBIPEn = 1) and associated pin is configured to enable the pullup device, KBEDGn can be used to reconfigure the pullup as a pulldown device.

Figure 8-1. MC9S08QG8/4 Block Diagram Highlighting ACMP Block and Pins



Chapter 9 Analog-to-Digital Converter (S08ADC10V1)

9.1 Introduction

The 10-bit analog-to-digital converter (ADC) is a successive approximation ADC designed for operation within an integrated microcontroller system-on-chip.

Figure 9-1 shows the MC9S08QG8/4 with the ADC module and pins highlighted.



Field	Description
5 ACFE	 Compare Function Enable — ACFE is used to enable the compare function. 0 Compare function disabled 1 Compare function enabled
4 ACFGT	 Compare Function Greater Than Enable — ACFGT is used to configure the compare function to trigger when the result of the conversion of the input being monitored is greater than or equal to the compare value. The compare function defaults to triggering when the result of the compare of the input being monitored is less than the compare value. 0 Compare triggers when input is less than compare level 1 Compare triggers when input is greater than or equal to compare level

Table 9-4. ADCSC2 Register Field Descriptions (continued)

9.3.3 Data Result High Register (ADCRH)

ADCRH contains the upper two bits of the result of a 10-bit conversion. When configured for 8-bit conversions both ADR8 and ADR9 are equal to zero. ADCRH is updated each time a conversion completes except when automatic compare is enabled and the compare condition is not met. In 10-bit MODE, reading ADCRH prevents the ADC from transferring subsequent conversion results into the result registers until ADCRL is read. If ADCRL is not read until after the next conversion is completed, then the intermediate conversion result will be lost. In 8-bit mode there is no interlocking with ADCRL. In the case that the MODE bits are changed, any data in ADCRH becomes invalid.



Figure 9-6. Data Result High Register (ADCRH)

9.3.4 Data Result Low Register (ADCRL)

ADCRL contains the lower eight bits of the result of a 10-bit conversion, and all eight bits of an 8-bit conversion. This register is updated each time a conversion completes except when automatic compare is enabled and the compare condition is not met. In 10-bit mode, reading ADCRH prevents the ADC from transferring subsequent conversion results into the result registers until ADCRL is read. If ADCRL is not read until the after next conversion is completed, then the intermediate conversion results will be lost. In 8-bit mode, there is no interlocking with ADCRH. In the case that the MODE bits are changed, any data in ADCRL becomes invalid.



Internal Clock Source (S08ICSV1)

10.1.4.5 FLL Bypassed External (FBE)

In FLL bypassed external mode, the FLL is enabled and controlled by an external reference clock, but is bypassed. The ICS supplies a clock derived from the external reference clock. The external reference clock can be an external crystal/resonator supplied by an OSC controlled by the ICS, or it can be another external clock source. The BDC clock is supplied from the FLL.

10.1.4.6 FLL Bypassed External Low Power (FBELP)

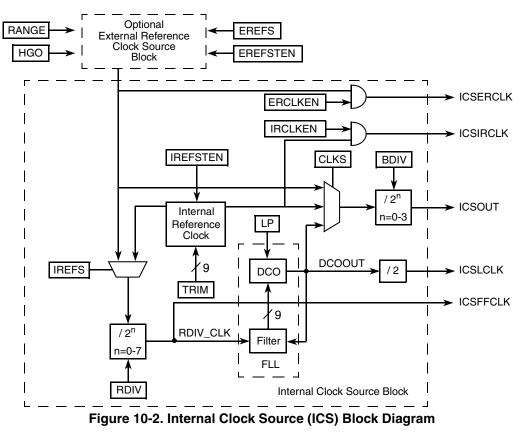
In FLL bypassed external low power mode, the FLL is disabled and bypassed, and the ICS supplies a clock derived from the external reference clock. The external reference clock can be an external crystal/resonator supplied by an OSC controlled by the ICS, or it can be another external clock source. The BDC clock is not available.

10.1.4.7 Stop (STOP)

In stop mode, the FLL is disabled and the internal or external reference clock can be selected to be enabled or disabled. The BDC clock is not available. ICS does not provide an MCU clock source.

10.1.5 Block Diagram

This section contains the ICS block diagram.

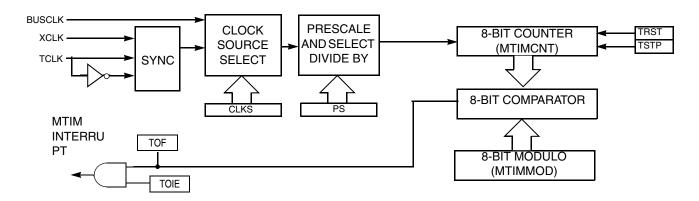




Modulo Timer (S08MTIMV1)

13.1.4 Block Diagram

The block diagram for the modulo timer module is shown Figure 13-2.





13.2 External Signal Description

The MTIM includes one external signal, TCLK, used to input an external clock when selected as the MTIM clock source. The signal properties of TCLK are shown in Table 13-1.

Table 13-1. Signal Properties

Signal	Function	
TCLK	External clock source input into MTIM	Ι

The TCLK input must be synchronized by the bus clock. Also, variations in duty cycle and clock jitter must be accommodated. Therefore, the TCLK signal must be limited to one-fourth of the bus frequency.

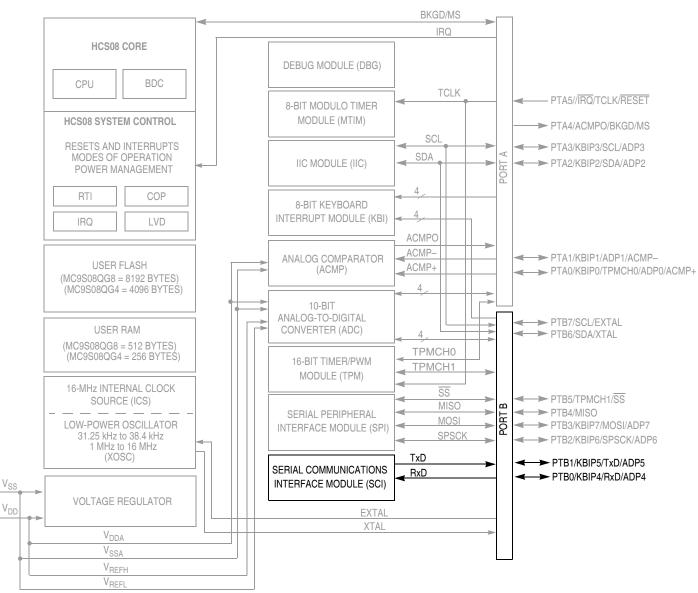
The TCLK pin can be muxed with a general-purpose port pin. See the Pins and Connections chapter for the pin location and priority of this function.

13.3 Register Definition

Figure 13-3 is a summary of MTIM registers.



Chapter 14 Serial Communications Interface (S08SCIV3)



NOTES:

¹ Not all pins or pin functions are available on all devices, see Table 1-1 for available functions on each device.

- ² Port pins are software configurable with pullup device if input port.
- ³ Port pins are software configurable for output drive strength.
- ⁴ Port pins are software configurable for output slew rate control.
- ⁵ IRQ contains a software configurable (IRQPDD) pullup/pulldown device if PTA5 enabled as IRQ pin function (IRQPE = 1).
- ⁶ RESET contains integrated pullup device if PTA5 enabled as reset pin function (RSTPE = 1).
- ⁷ PTA4 contains integrated pullup device if BKGD enabled (BKGDPE = 1).
- ⁸ SDA and SCL pin locations can be repositioned under software control (IICPS), defaults on PTA2 and PTA3.
- ⁹ When pin functions as KBI (KBIPEn = 1) and associated pin is configured to enable the pullup device, KBEDGn can be used to reconfigure the pullup as a pulldown device.

Figure 14-1. MC9S08QG8/4 Block Diagram Highlighting SCI Block and Pins



14.2.5 SCI Status Register 2 (SCIS2)

This register has one read-only status flag. Writes have no effect.

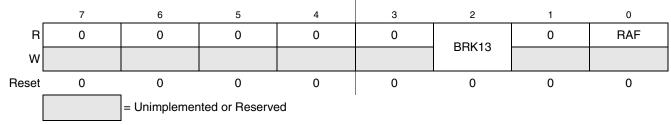


Figure 14-10. SCI Status Register 2 (SCIS2)

Table 14-6. SCIS2 Register Field Descriptions

Field	Description						
2 BRK13	 Break Character Length — BRK13 is used to select a longer break character length. Detection of a framing error is not affected by the state of this bit. 0 Break character is 10 bit times (11 if M = 1) 1 Break character is 13 bit times (14 if M = 1) 						
0 RAF	 Receiver Active Flag — RAF is set when the SCI receiver detects the beginning of a valid start bit, and RAF is cleared automatically when the receiver detects an idle line. This status flag can be used to check whether an SCI character is being received before instructing the MCU to go to stop mode. SCI receiver idle waiting for a start bit. SCI receiver active (RxD input not idle). 						

14.2.6 SCI Control Register 3 (SCIC3)

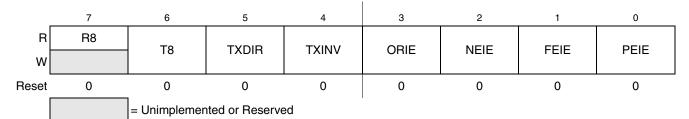


Figure 14-11. SCI Control Register 3 (SCIC3)

Table 14-7. SCIC3 Register Field Descriptions

Field	Description							
7 R8	Ninth Data Bit for Receiver — When the SCI is configured for 9-bit data ($M = 1$), R8 can be thought of as a ninth receive data bit to the left of the MSB of the buffered data in the SCID register. When reading 9-bit data, read R8 before reading SCID because reading SCID completes automatic flag clearing sequences which could allow R8 and SCID to be overwritten with new data.							
6 T8	Ninth Data Bit for Transmitter — When the SCI is configured for 9-bit data ($M = 1$), T8 may be thought of as a ninth transmit data bit to the left of the MSB of the data in the SCID register. When writing 9-bit data, the entire 9-bit value is transferred to the SCI shift register after SCID is written so T8 should be written (if it needs to change from its previous value) before SCID is written. If T8 does not need to change in the new value (such as when it is used to generate mark or space parity), it need not be written each time SCID is written.							



Serial Peripheral Interface (S08SPIV3)

15.5 Functional Description

An SPI transfer is initiated by checking for the SPI transmit buffer empty flag (SPTEF = 1) and then writing a byte of data to the SPI data register (SPID) in the master SPI device. When the SPI shift register is available, this byte of data is moved from the transmit data buffer to the shifter, SPTEF is set to indicate there is room in the buffer to queue another transmit character if desired, and the SPI serial transfer starts.

During the SPI transfer, data is sampled (read) on the MISO pin at one SPSCK edge and shifted, changing the bit value on the MOSI pin, one-half SPSCK cycle later. After eight SPSCK cycles, the data that was in the shift register of the master has been shifted out the MOSI pin to the slave while eight bits of data were shifted in the MISO pin into the master's shift register. At the end of this transfer, the received data byte is moved from the shifter into the receive data buffer and SPRF is set to indicate the data can be read by reading SPID. If another byte of data is waiting in the transmit buffer at the end of a transfer, it is moved into the shifter, SPTEF is set, and a new transfer is started.

Normally, SPI data is transferred most significant bit (MSB) first. If the least significant bit first enable (LSBFE) bit is set, SPI data is shifted LSB first.

When the SPI is configured as a slave, its \overline{SS} pin must be driven low before a transfer starts and \overline{SS} must stay low throughout the transfer. If a clock format where CPHA = 0 is selected, \overline{SS} must be driven to a logic 1 between successive transfers. If CPHA = 1, \overline{SS} may remain low between successive transfers. See Section 15.5.1, "SPI Clock Formats" for more details.

Because the transmitter and receiver are double buffered, a second byte, in addition to the byte currently being shifted out, can be queued into the transmit data buffer, and a previously received character can be in the receive data buffer while a new character is being shifted in. The SPTEF flag indicates when the transmit buffer has room for a new character. The SPRF flag indicates when a received character is available in the receive data buffer. The received character must be read out of the receive buffer (read SPID) before the next transfer is finished or a receive overrun error results.

In the case of a receive overrun, the new data is lost because the receive buffer still held the previous character and was not ready to accept the new data. There is no indication for such an overrun condition so the application system designer must ensure that previous data has been read from the receive buffer before a new transfer is initiated.

15.5.1 SPI Clock Formats

To accommodate a wide variety of synchronous serial peripherals from different manufacturers, the SPI system has a clock polarity (CPOL) bit and a clock phase (CPHA) control bit to select one of four clock formats for data transfers. CPOL selectively inserts an inverter in series with the clock. CPHA chooses between two different clock phase relationships between the clock and data.

Figure 15-10 shows the clock formats when CPHA = 1. At the top of the figure, the eight bit times are shown for reference with bit 1 starting at the first SPSCK edge and bit 8 ending one-half SPSCK cycle after the sixteenth SPSCK edge. The MSB first and LSB first lines show the order of SPI data bits depending on the setting in LSBFE. Both variations of SPSCK polarity are shown, but only one of these waveforms applies for a specific transfer, depending on the value in CPOL. The SAMPLE IN waveform applies to the MOSI input of a slave or the MISO input of a master. The MOSI waveform applies to the



15.5.2 SPI Interrupts

There are three flag bits, two interrupt mask bits, and one interrupt vector associated with the SPI system. The SPI interrupt enable mask (SPIE) enables interrupts from the SPI receiver full flag (SPRF) and mode fault flag (MODF). The SPI transmit interrupt enable mask (SPTIE) enables interrupts from the SPI transmit buffer empty flag (SPTEF). When one of the flag bits is set, and the associated interrupt mask bit is set, a hardware interrupt request is sent to the CPU. If the interrupt mask bits are cleared, software can poll the associated flag bits instead of using interrupts. The SPI interrupt service routine (ISR) should check the flag bits to determine what event caused the interrupt. The service routine should also clear the flag bit(s) before returning from the ISR (usually near the beginning of the ISR).

15.5.3 Mode Fault Detection

A mode fault occurs and the mode fault flag (MODF) becomes set when a master SPI device detects an error on the \overline{SS} pin (provided the \overline{SS} pin is configured as the mode fault input signal). The \overline{SS} pin is configured to be the mode fault input signal when MSTR = 1, mode fault enable is set (MODFEN = 1), and slave select output enable is clear (SSOE = 0).

The mode fault detection feature can be used in a system where more than one SPI device might become a master at the same time. The error is detected when a master's \overline{SS} pin is low, indicating that some other SPI device is trying to address this master as if it were a slave. This could indicate a harmful output driver conflict, so the mode fault logic is designed to disable all SPI output drivers when such an error is detected.

When a mode fault is detected, MODF is set and MSTR is cleared to change the SPI configuration back to slave mode. The output drivers on the SPSCK, MOSI, and MISO (if not bidirectional mode) are disabled.

MODF is cleared by reading it while it is set, then writing to the SPI control register 1 (SPIC1). User software should verify the error condition has been corrected before changing the SPI back to master mode.



Chapter 17 Development Support

17.1 Introduction

Development support systems in the HCS08 include the background debug controller (BDC) and the on-chip debug module (DBG). The BDC provides a single-wire debug interface to the target MCU that provides a convenient interface for programming the on-chip FLASH and other nonvolatile memories. The BDC is also the primary debug interface for development and allows non-intrusive access to memory data and traditional debug features such as CPU register modify, breakpoints, and single instruction trace commands.

In the HCS08 Family, address and data bus signals are not available on external pins. Debug is done through commands fed into the target MCU via the single-wire background debug interface. The debug module provides a means to selectively trigger and capture bus information so an external development system can reconstruct what happened inside the MCU on a cycle-by-cycle basis without having external access to the address and data signals.

17.1.1 Module Configuration

The alternate BDC clock source is the ICSLCLK. This clock source is selected by clearing the CLKSW bit in the BDCSCR register. For details on ICSLCLK, see Section 10.4, "Functional Description" of the ICS chapter.



Characteristic	Conditions	Symb	Min	Typ ¹	Max	Unit	Comment		
Conversion time	Short sample (ADLSMP=0)	t _{ADC}		20		ADCK cycles	See Table 9-12 for conversion		
(including sample time)	Long sample (ADLSMP=1)		_	40	_				
Sample time	Short sample (ADLSMP=0)	t _{ADS}		3.5	—	ADCK cycles	time variances		
	Long sample (ADLSMP=1)		-	23.5	—				
Total unadjusted error	10 bit mode	E _{TUE}	_	±1.5	±3.5	LSB ²	Includes		
	8 bit mode		_	±0.7	±1.5		quantization		
Differential	10 bit mode	DNL		±0.5	±1.0	LSB ²	Monotonicity and no missing codes guaranteed		
non-linearity	8 bit mode		_	±0.3	±0.5				
Integral non-linearity	10 bit mode	INL	_	±0.5	±1.0	LSB ²			
	8 bit mode		_	±0.3	±0.5				
Zero-scale error	10 bit mode	E _{ZS}	_	±1.5	±2.1	LSB ²	$V_{ADIN} = V_{SS}$		
	8 bit mode			±0.5	±0.7				
Full-scale error	10 bit mode	E _{FS}	0	±1.0	±1.5	LSB ²	$V_{ADIN} = V_{DD}$		
	8 bit mode		0	±0.5	±0.5				
Quantization error	10 bit mode	EQ		—	±0.5	LSB ²			
	8 bit mode		_	—	±0.5				
Input leakage error	10 bit mode	E _{IL}	0	±0.2	±4	LSB ²	Pad leakage ³ *		
	8 bit mode		0	±0.1	±1.2		R _{AS}		
Temp sensor slope	-40°C– 25°C	m	_	1.646	_	mV/°C			
	25°C– 85°C			1.769	—				
Temp sensor voltage	25°C	V _{TEMP25}	_	701.2	_	mV			

Table A-14. 3 Volt 10-bit ADC Characteristics (c	continued)
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¹ Typical values assume V_{DD} = 3.0 V, Temp = 25°C, f_{ADCK} = 1.0 MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
 ² 1 LSB = (V_{REFH} - V_{REFL})/2^N

³ Based on input pad leakage current. Refer to pad electricals.



Appendix B Ordering Information and Mechanical Drawings

Pin Count	Type Designator		Document No.		
8	DFN	FQ	98ARL10557D		
8	PDIP	PA	98ASB42420B		
8	NB SOIC	DN	98ASB42564B		

Table B-2. Package Information (continued)



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: INCH.
- A DIMENSION TO CENTER OF LEADS WHEN FORMED PARALLEL.
- A DIMENSIONS DOES NOT INCLUDE MOLD FLASH.
- 5. ROUNDED CORNERS OPTIONAL.
- 6. 648-01 THRU -08 OBSOLETE, NEW STANDARD 648-09.

	MILLIM	ETERS	RS INCHES MILLIMETERS		INCHES				
DIM	MIN	MAX	MIN	MAX	DIM	MIN	MAX	MIN	MAX
A	18.80	19.55	0.740	0.770					
В	6.35	6.85	0.250	0.270					
С	3.69	4.44	0.145	0.175					
D	0.39	0.53	0.015	0.021					
F	1.02	1.77	0.040	0.070					
G	2.54	BSC	0.1	IOO BSC					
Н	1.27	BSC	C 0.050 BSC						
J	0.21	0.38	0.008	0.015					
K	2.80	3.30	0.110	0.130					
L	7.50	7.74	0.295	0.305					
М	0.	10°	0.	10*					
S	0.51	1.01	0.020	0.040					
© FF	© FREESCALE SEMICONDUCTOR, INC. MECHANICA				AL OUTLINE PRINT VERSION NOT TO SO				DT TO SCALE
TITLE	TITLE:				DOCU	Ment no	REV: T		
	16 LD PDIP				CASE NUMBER: 648-08 19 MAY 20				19 MAY 2005
				STANDARD: NON-JEDEC					



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Asia/Pacific:

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